

ABSTRACT OF THE DISCLOSURE

With an Al-Cu bonded structure, an Ag layer can be remained at the Al-Cu bonding interlayer, providing ductile deformation behavior and a tensile strength at the bonded interlayer similar to that of the Al base material. This results in superior bonding characteristics. Furthermore, a thin Al-Cu bonded structure can be obtained as a result of using the Al-Cu dissimilar material bonded section, which has superior workability, as the base material to perform rolling for wall-thickness reduction. The thin Al-Cu structure has superior dimensional accuracy and can meet diverse dimensional demands. The structure combines the light weight of Al with its particular heat transfer and heat dissipative characteristics and anti-corrosive properties of Cu, allowing it to meet the compact, thin, light-weight, and high-performance needs of electronic devices. The structure can be widely used in heat exchangers and heat transfer devices.